

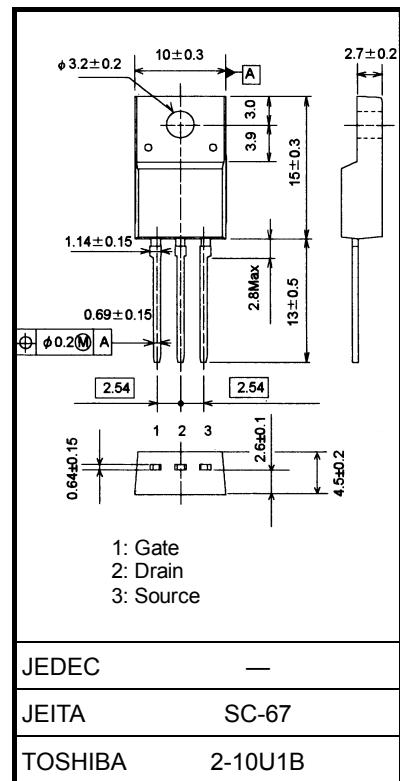
Silicon N-Channel MOS Type (π -MOSVI)

2SK3797

Switching Regulator Applications

Unit: mm

- Low drain-source ON resistance: $R_{DS(ON)} = 0.32 \Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 7.5 \text{ S}$ (typ.)
- Low leakage current: $I_{DSS} = 100 \mu\text{A}$ ($V_{DS} = 600 \text{ V}$)
- Enhancement model: $V_{th} = 2.0$ to 4.0 V ($V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$)



Weight: 1.7 g (typ.)

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristic	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	600	V
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)	V_{DGR}	600	V
Gate-source voltage	V_{GSS}	± 30	V
Drain current	DC (Note 1)	I_D	13
	Pulse ($t = 1 \text{ ms}$) (Note 1)	I_{DP}	52
Drain power dissipation ($T_c = 25^\circ\text{C}$)	P_D	50	W
Single pulse avalanche energy (Note 2)	E_{AS}	1033	mJ
Avalanche current	I_{AR}	13	A
Repetitive avalanche energy (Note 3)	E_{AR}	5.0	mJ
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature range	T_{stg}	-55 to 150	$^\circ\text{C}$

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

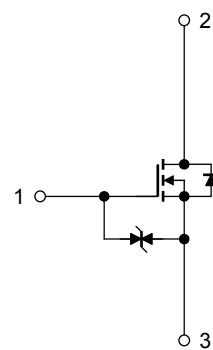
Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th}(ch-c)$	2.5	$^\circ\text{C}/\text{W}$
Thermal resistance, channel to ambient	$R_{th}(ch-a)$	62.5	$^\circ\text{C}/\text{W}$

Note 1: Ensure that the channel temperature does not exceed 150°C .

Note 2: $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 10.7 \text{ mH}$, $I_{AR} = 13 \text{ A}$, $R_G = 25 \Omega$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



Electrical Characteristics ($T_a = 25^\circ C$)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit	
Gate leakage current	I_{GSS}	$V_{GS} = \pm 25 V, V_{DS} = 0 V$	—	—	± 10	μA	
Gate-source breakdown voltage	$V_{(BR) GSS}$	$I_G = \pm 10 \mu A, V_{DS} = 0 V$	± 30	—	—	V	
Drain cutoff current	I_{DSS}	$V_{DS} = 600 V, V_{GS} = 0 V$	—	—	100	μA	
Drain-source breakdown voltage	$V_{(BR) DSS}$	$I_D = 10 mA, V_{GS} = 0 V$	600	—	—	V	
Gate threshold voltage	V_{th}	$V_{DS} = 10 V, I_D = 1 mA$	2.0	—	4.0	V	
Drain-source ON resistance	$R_{DS (\text{ON})}$	$V_{GS} = 10 V, I_D = 6.5 A$	—	0.32	0.43	Ω	
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 10 V, I_D = 7.0 A$	2.1	7.5	—	S	
Input capacitance	C_{iss}	$V_{DS} = 25 V, V_{GS} = 0 V, f = 1 \text{ MHz}$	—	3100	—	pF	
Reverse transfer capacitance	C_{rss}		—	20	—		
Output capacitance	C_{oss}		—	270	—		
Switching time	Rise time	t_r	 V_{GS} (0 V to 10 V)	—	60	—	ns
	Turn-on time	t_{on}		—	110	—	
	Fall time	t_f		—	50	—	
	Turn-off time	t_{off}		—	215	—	
Total gate charge	Q_g	$V_{DD} \approx 400 V, V_{GS} = 10 V, I_D = 13 A$	—	62	—	nC	
Gate-source charge	Q_{gs}		—	40	—		
Gate-drain charge	Q_{gd}		—	22	—		

Source-Drain Ratings and Characteristics ($T_a = 25^\circ C$)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	—	—	—	13	A
Pulse drain reverse current (Note 1)	I_{DRP}	—	—	—	52	A
Forward voltage (diode)	V_{DSF}	$I_{DR} = 13 A, V_{GS} = 0 V$	—	—	-1.7	V
Reverse recovery time	t_{rr}	$I_{DR} = 13 A, V_{GS} = 0 V,$ $dI_{DR}/dt = 100 A/\mu s$	—	1050	—	ns
Reverse recovery charge	Q_{rr}		—	15	—	μC

Marking